

Now Available!

THE WORLDWIDE IC PACKAGING MARKET

2011 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Update on Japan
 - ◆ Semiconductor Industry Analysis
- **Worldwide IC Packaging Market Forecasts, 2009–2015**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range
- **Contract IC Packaging Market Forecasts, 2009–2015**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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The Worldwide IC Packaging Market, 2011 Edition

Synopsis

The semiconductor industry's recovery in 2010 following the 2008-2009 recession was unprecedented, with one of the best growth years in its history. The estimated worldwide IC growth was 28.9% in terms of units and 31.3% in terms of revenue. Demand is being driven by wireless portable devices such as the iPhone and iPad which is far exceeding the growth of the overall economy.

New Venture Research (NVR), in the **2011 Edition of The Worldwide IC Packaging Market**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market.

The report begins with the latest updates on Japan, mergers and acquisitions, historic and future unit and revenue graphs, and a SATS company overview.

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents NVR's continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

The Worldwide IC Packaging Market, 2011 Edition continues NVR's leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$2995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$250 each and a corporate license is \$1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$500.

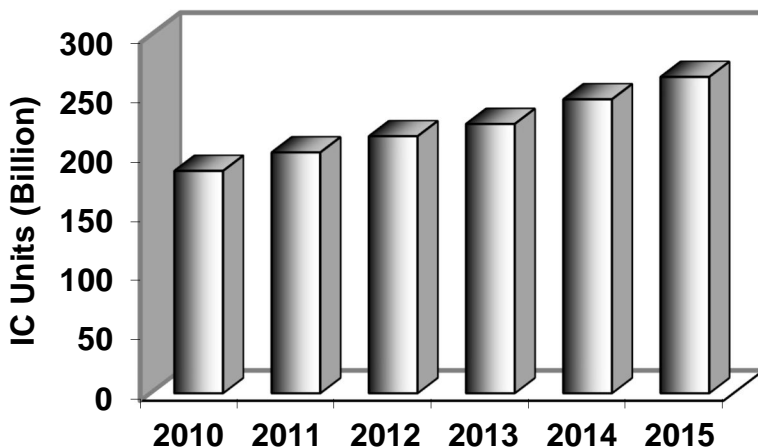


Figure 1 IC Unit Forecast

About the Author

Sandra Winkler is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry more than 20 years ago. Ms. Winkler has authored widely cited reports on IC packaging since 1995 for Electronic Trend Publications (ETP) which is now NVR. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

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DSP
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Flash
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Digital Bipolar
Standard Logic
Gate Arrays
Cell-Based and PLD
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Amplifiers
Interfaces
Voltage Regulators
Data Converters
Custom Analog

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IC Package Forecast by Package Family

DIP
SOT
SO
TSOP
DFN
CC
QFP
QFN
PGA
BGA
FBGA
WLP
DCA

Chapter 6: Packaging Contractor Market

Market Overview

Forecasts by Package Family

DIP
SOT
SO
TSOP
DFN
CC
QFP
QFN
PGA
BGA
FBGA
WLP

Unit, Revenue, and Pricing Forecasts

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Amkor	Millennium Microtech
Anst China	Naito Densai Kogyo
ASE	Nantong Fujitsu
Azimuth	NxGEN
Carsem	OSE
China Wafer Level CSP	Powertech
ChipMOS	Shinko Electric
CORWIL Technology	Signetics
EEMS	Siliconware
FlipChip Int'l	SPEL
Hana	STATS ChipPAC
Hana Micron	Tianshui Huatian Tech
I2A	Unisem
IDS Electronics	UTAC
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 Voltage Regulators
 Data Converters
 Custom Analog

DIP Forecasts—3 I/O Ranges
SOT Forecasts
SO Forecasts—3 I/O Ranges
TSOP Forecasts—3 I/O Ranges
DFN Forecasts—2 I/O Ranges
CC Forecasts—2 I/O Ranges
QFP Forecasts—2 I/O Ranges
QFN Forecasts—4 I/O Ranges
PGA Forecasts—2 I/O Ranges
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Contractor Total Forecast
Contractor DIP Forecast
Contractor SOT Forecast
Contractor SO Forecast
Contractor TSOP Forecast
Contractor DFN Forecast
Contractor CC Forecast
Contractor QFP Forecast
Contractor QFN Forecast
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Contractor FBGA Forecast
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